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Details

Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SO
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908qt1amdwe

1.4 Pin Assignments

The MC68HC908QT4A, MC68H908QT2A, and MC68HC098QT1A are available in 8-pin packages. The MC68HC908QY4A, MC68HC908QY2A, and MC68HC908QY1A are available in 16-pin packages. Figure 1-2 shows the pin assignment for these packages.

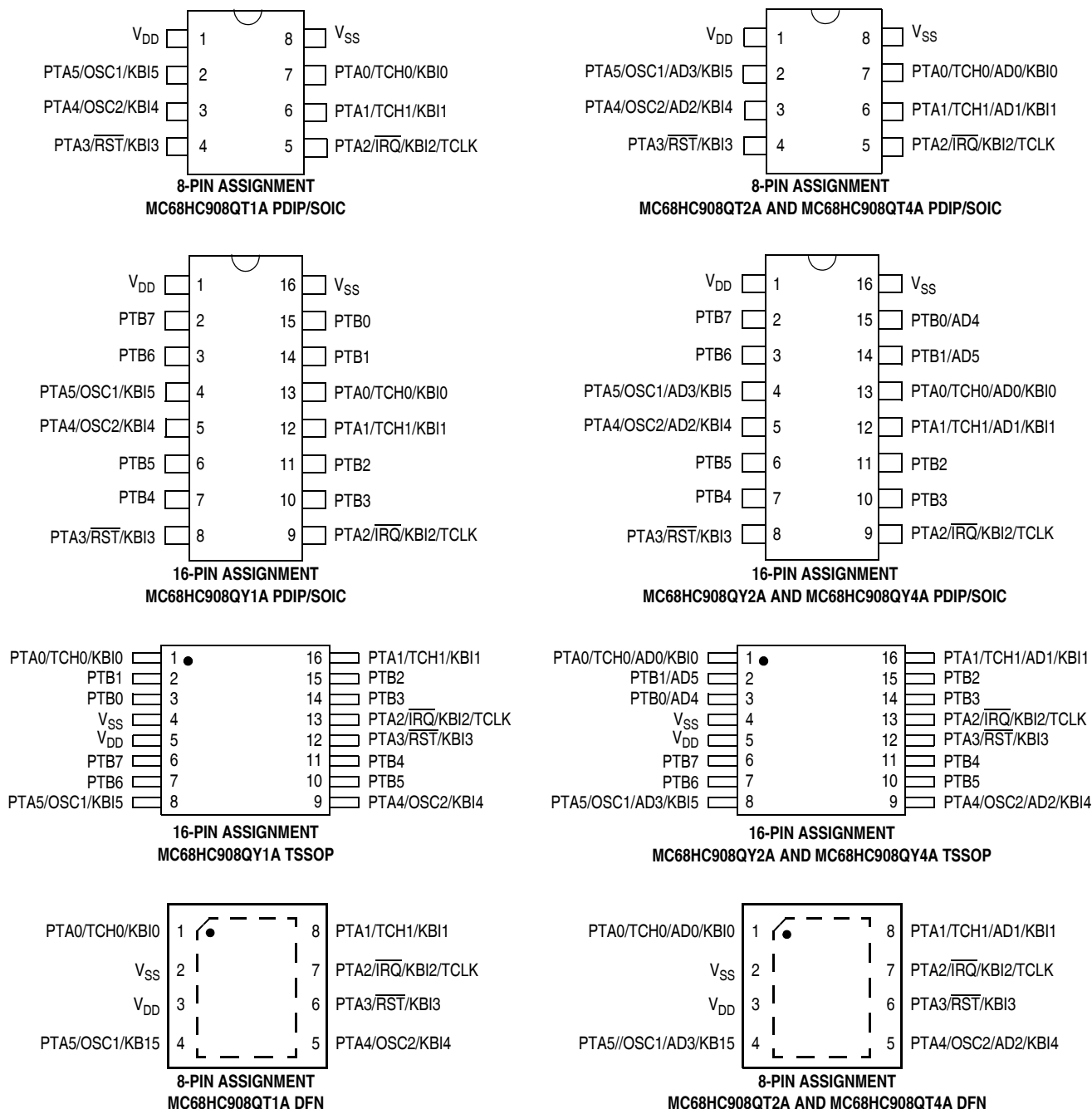


Figure 1-2. MCU Pin Assignments

Addr.	Register Name	Bit 7	6	5	4	3	2	1	Bit 0	
\$0028	TIM Channel 1 Status and Control Register (TSC1) See page 135.	Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
\$0029	TIM Channel 1 Register High (TCH1H) See page 137.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	Indeterminate after reset							
\$002A	TIM Channel 1 Register Low (TCH1L) See page 137.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	Indeterminate after reset							
\$002B ↓ \$0035	Reserved									
\$0036	Oscillator Status and Control Register (OSCSC) See page 100.	Read:	OSCOPT1	OSCOPT0	ICFS1	ICFS0	ECFS1	ECFS0	ECGON	ECGST
		Write:								
		Reset:	0	0	1	0	0	0	0	0
\$0037	Reserved									
\$0038	Oscillator Trim Register (OSCTRIM) See page 101.	Read:	TRIM7	TRIM6	TRIM5	TRIM4	TRIM3	TRIM2	TRIM1	TRIM0
		Write:								
		Reset:	1	0	0	0	0	0	0	0
\$0039 ↓ \$003B	Reserved									
\$003C	ADC10 Status and Control Register (ADSCR) See page 46.	Read:	COCO	AIEN	ADCO	ADCH4	ADCH3	ADCH2	ADCH1	ADCH0
		Write:								
		Reset:	0	0	0	1	1	1	1	1
\$003D	ADC10 Data Register High (ADRH) See page 48.	Read:	0	0	0	0	0	0	AD9	AD8
		Write:	R	R	R	R	R	R	R	R
		Reset:	0	0	0	0	0	0	0	0
\$003E	ADC10 Data Register Low (ADRL) See page 48.	Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
		Write:	R	R	R	R	R	R	R	R
		Reset:	0	0	0	0	0	0	0	0
\$003F	ADC10 Clock Register (ADCLK) See page 48.	Read:	ADLPC	ADIV1	ADIV0	ADICLK	MODE1	MODE0	ADLSMP	ACLKEN
		Write:								
		Reset:	0	0	0	0	0	0	0	0

= Unimplemented
 R = Reserved
 U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 3 of 5)

charging. If externally available, connect the V_{REFL} pin to the same potential as V_{SSA} at the single point ground location.

3.7.5 ADC10 Channel Pins (ADn)

The ADC10 has multiple input channels. Empirical data shows that capacitors on the analog inputs improve performance in the presence of noise or when the source impedance is high. 0.01 μ F capacitors with good high-frequency characteristics are sufficient. These capacitors are not necessary in all cases, but when used they must be placed as close as possible to the package pins and be referenced to V_{SSA} .

3.8 Registers

These registers control and monitor operation of the ADC10:

- ADC10 status and control register, ADSCR
- ADC10 data registers, ADRH and ADRL
- ADC10 clock register, ADCLK

3.8.1 ADC10 Status and Control Register

This section describes the function of the ADC10 status and control register (ADSCR). Writing ADSCR aborts the current conversion and initiates a new conversion (if the ADCH[4:0] bits are equal to a value other than all 1s).

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	COCO	AIEN	ADCO	ADCH4	ADCH3	ADCH2	ADCH1	ADCH0
Write:								
Reset:	0	0	0	1	1	1	1	1

Figure 3-3. ADC10 Status and Control Register (ADSCR)

COCO — Conversion Complete Bit

COCO is a read-only bit which is set each time a conversion is completed. This bit is cleared whenever the status and control register is written or whenever the data register (low) is read.

- 1 = Conversion completed
- 0 = Conversion not completed

AIEN — ADC10 Interrupt Enable Bit

When this bit is set, an interrupt is generated at the end of a conversion. The interrupt signal is cleared when the data register is read or the status/control register is written.

- 1 = ADC10 interrupt enabled
- 0 = ADC10 interrupt disabled

ADCO — ADC10 Continuous Conversion Bit

When this bit is set, the ADC10 will begin to convert samples continuously (continuous conversion mode) and update the result registers at the end of each conversion, provided the ADCH[4:0] bits do not decode to all 1s. The ADC10 will continue to convert until the MCU enters reset, the MCU enters stop mode (if ACLKEN is clear), ADCLK is written, or until ADSCR is written again. If stop is entered (with ACLKEN low), continuous conversions will cease and can be restarted only with a write to ADSCR. Any write to ADSCR with ADCO set and the ADCH bits not all 1s will abort the current conversion and begin continuous conversions.

ADIV[1:0] — ADC10 Clock Divider Bits

ADIV1 and ADIV0 select the divide ratio used by the ADC10 to generate the internal clock ADCK. Table 3-3 shows the available clock configurations.

Table 3-3. ADC10 Clock Divide Ratio

ADIV1	ADIV0	Divide Ratio (ADIV)	Clock Rate
0	0	1	Input clock ÷ 1
0	1	2	Input clock ÷ 2
1	0	4	Input clock ÷ 4
1	1	8	Input clock ÷ 8

ADICLK — Input Clock Select Bit

If ACLKEN is clear, ADICLK selects either the bus clock or an alternate clock source as the input clock source to generate the internal clock ADCK. If the alternate clock source is less than the minimum clock speed, use the internally-generated bus clock as the clock source. As long as the internal clock ADCK, which is equal to the selected input clock divided by ADIV, is at a frequency (f_{ADCK}) between the minimum and maximum clock speeds (considering ALPC), correct operation can be guaranteed.

1 = The internal bus clock is selected as the input clock source

0 = The alternate clock source IS SELECTED

MODE[1:0] — 10- or 8-Bit or Hardware Triggered Mode Selection

These bits select 10- or 8-bit operation. The successive approximation converter generates a result that is rounded to 8- or 10-bit value based on the mode selection. This rounding process sets the transfer function to transition at the midpoint between the ideal code voltages, causing a quantization error of $\pm 1/2LSB$.

Reset returns 8-bit mode.

00 = 8-bit, right-justified, ADSCR software triggered mode enabled

01 = 10-bit, right-justified, ADSCR software triggered mode enabled

10 = Reserved

11 = 10-bit, right-justified, hardware triggered mode enabled

ADLSMP — Long Sample Time Configuration

This bit configures the sample time of the ADC10 to either 3.5 or 23.5 ADCK clock cycles. This adjusts the sample period to allow higher impedance inputs to be accurately sampled or to maximize conversion speed for lower impedance inputs. Longer sample times can also be used to lower overall power consumption in continuous conversion mode if high conversion rates are not required.

1 = Long sample time (23.5 cycles)

0 = Short sample time (3.5 cycles)

ACLKEN — Asynchronous Clock Source Enable

This bit enables the asynchronous clock source as the input clock to generate the internal clock ADCK, and allows operation in stop mode. The asynchronous clock source will operate between 1 MHz and 2 MHz if ADLPC is clear, and between 0.5 MHz and 1 MHz if ADLPC is set.

1 = The asynchronous clock is selected as the input clock source (the clock generator is only enabled during the conversion)

0 = ADICLK specifies the input clock source and conversions will not continue in stop mode

Chapter 5

Configuration Register (CONFIG)

5.1 Introduction

This section describes the configuration registers (CONFIG1 and CONFIG2). The configuration registers enable or disable the following options:

- Stop mode recovery time ($32 \times \text{BUSCLKX4}$ cycles or $4096 \times \text{BUSCLKX4}$ cycles)
- STOP instruction
- Computer operating properly module (COP)
- COP reset period (COPRS): $8176 \times \text{BUSCLKX4}$ or $262,128 \times \text{BUSCLKX4}$
- Low-voltage inhibit (LVI) enable and trip voltage selection
- Auto wakeup timeout period
- Allow clock source to remain enabled in STOP
- Enable $\overline{\text{IRQ}}$ pin
- Disable $\overline{\text{IRQ}}$ pin pullup device
- Enable $\overline{\text{RST}}$ pin

5.2 Functional Description

The configuration registers are used in the initialization of various options. The configuration registers can be written once after each reset. Most of the configuration register bits are cleared during reset. Since the various options affect the operation of the microcontroller unit (MCU) it is recommended that this register be written immediately after reset. The configuration registers are located at \$001E and \$001F, and may be read at anytime.

NOTE

The CONFIG registers are one-time writable by the user after each reset. Upon a reset, the CONFIG registers default to predetermined settings as shown in [Figure 5-1](#) and [Figure 5-2](#).

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IRQPUD	IRQEN	R	R	R	R	OSCENINSTOP	RSTEN
Write:								
Reset:	0	0	0	0	0	0	0	U
POR:	0	0	0	0	0	0	0	0

R = Reserved U = Unaffected

Figure 5-1. Configuration Register 2 (CONFIG2)

Table 7-1. Instruction Set Summary (Sheet 3 of 6)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles	
			V	H	I	N	Z					C
CLR <i>opr</i> CLRA CLR _X CLR _H CLR <i>opr,X</i> CLR ,X CLR <i>opr,SP</i>	Clear	M ← \$00 A ← \$00 X ← \$00 H ← \$00 M ← \$00 M ← \$00 M ← \$00	0	-	-	0	1	-	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd ff ff	3 1 1 1 3 2 4
CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr,X</i> CMP <i>opr,X</i> CMP ,X CMP <i>opr,SP</i> CMP <i>opr,SP</i>	Compare A with M	(A) - (M)	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
COM <i>opr</i> COMA COM _X COM <i>opr,X</i> COM ,X COM <i>opr,SP</i>	Complement (One's Complement)	M ← (M) = \$FF - (M) A ← (A) = \$FF - (M) X ← (X) = \$FF - (M) M ← (M) = \$FF - (M) M ← (M) = \$FF - (M) M ← (M) = \$FF - (M)	0	-	-	†	†	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff ff	4 1 1 4 3 5
CPHX # <i>opr</i> CPHX <i>opr</i>	Compare H:X with M	(H:X) - (M:M + 1)	†	-	-	†	†	†	IMM DIR	65 75	ii ii+1 dd	3 4
CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX ,X CPX <i>opr,X</i> CPX <i>opr,X</i> CPX <i>opr,SP</i> CPX <i>opr,SP</i>	Compare X with M	(X) - (M)	†	-	-	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
DAA	Decimal Adjust A	(A) ₁₀	U	-	-	†	†	†	INH	72		2
DBNZ <i>opr,rel</i> DBNZ _A <i>rel</i> DBNZ _X <i>rel</i> DBNZ <i>opr,X,rel</i> DBNZ _{X,rel} DBNZ <i>opr,SP,rel</i>	Decrement and Branch if Not Zero	A ← (A) - 1 or M ← (M) - 1 or X ← (X) - 1 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 4 + <i>rel</i> ? (result) ≠ 0	-	-	-	-	-	-	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	5 3 3 5 4 6
DEC <i>opr</i> DECA DEC _X DEC <i>opr,X</i> DEC ,X DEC <i>opr,SP</i>	Decrement	M ← (M) - 1 A ← (A) - 1 X ← (X) - 1 M ← (M) - 1 M ← (M) - 1 M ← (M) - 1	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd ff ff	4 1 1 4 3 5
DIV	Divide	A ← (H:A)/(X) H ← Remainder	-	-	-	-	†	†	INH	52		7
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr,X</i> EOR <i>opr,X</i> EOR ,X EOR <i>opr,SP</i> EOR <i>opr,SP</i>	Exclusive OR M with A	A ← (A ⊕ M)	0	-	-	†	†	-	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh ll ee ff ff ff ff ee ff	2 3 4 4 3 2 4 5
INC <i>opr</i> INCA INC _X INC <i>opr,X</i> INC ,X INC <i>opr,SP</i>	Increment	M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1 M ← (M) + 1	†	-	-	†	†	-	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd ff ff	4 1 1 4 3 5

8.4 Interrupts

The following IRQ source can generate interrupt requests:

- Interrupt flag (IRQF) — The IRQF bit is set when the $\overline{\text{IRQ}}$ pin is asserted based on the IRQ mode. The IRQ interrupt mask bit, IMASK, is used to enable or disable IRQ interrupt requests.

8.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

8.5.1 Wait Mode

The IRQ module remains active in wait mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of wait mode.

8.5.2 Stop Mode

The IRQ module remains active in stop mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of stop mode.

8.6 IRQ Module During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

8.7 I/O Signals

The IRQ module does not share its pin with any module on this MCU.

8.7.1 IRQ Input Pins ($\overline{\text{IRQ}}$)

The $\overline{\text{IRQ}}$ pin provides a maskable external interrupt source. The $\overline{\text{IRQ}}$ pin contains an internal pullup device.

11.8 Registers

The oscillator module contains two registers:

- Oscillator status and control register (OSCSC)
- Oscillator trim register (OSCTRIM)

11.8.1 Oscillator Status and Control Register

The oscillator status and control register (OSCSC) contains the bits for switching between internal and external clock sources. If the application uses an external crystal, bits in this register are used to select the crystal oscillator amplifier necessary for the desired crystal. While running off the internal clock source, the user can use bits in this register to select the internal clock source frequency.

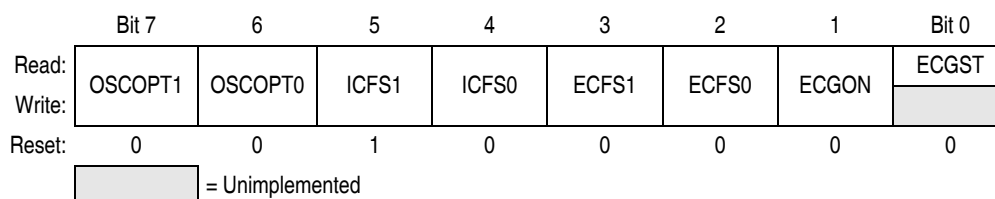


Figure 11-4. Oscillator Status and Control Register (OSCSC)

OSCOPT1:OSCOPT0 — OSC Option Bits

These read/write bits allow the user to change the clock source for the MCU. The default reset condition has the bus clock being derived from the internal oscillator. See [11.3.2.2 Internal to External Clock Switching](#) for information on changing clock sources.

OSCOPT1	OSCOPT0	Oscillator Modes
0	0	Internal oscillator (frequency selected using ICFSx bits)
0	1	External oscillator clock
1	0	External RC
1	1	External crystal (range selected using ECFSx bits)

ICFS1:ICFS0 — Internal Clock Frequency Select Bits

These read/write bits enable the frequency to be increased for applications requiring a faster bus clock when running off the internal oscillator. The WAIT instruction has no effect on the oscillator logic. BUSCLKX2 and BUSCLKX4 continue to drive to the SIM module.

ICFS1	ICFS0	Internal Clock Frequency
0	0	4.0 MHz
0	1	8.0 MHz
1	0	12.8 MHz — default reset condition
1	1	Reserved



13.6.2.1 Interrupt Status Register 1

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF6	IF5	IF4	IF3	IF2	IF1	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-11. Interrupt Status Register 1 (INT1)

IF1–IF6 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

Bit 0, 1 — Always read 0

13.6.2.2 Interrupt Status Register 2

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF14	IF13	IF12	IF11	IF10	IF9	IF8	IF7
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-12. Interrupt Status Register 2 (INT2)

IF7–IF14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

13.6.2.3 Interrupt Status Register 3

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF22	IF21	IF20	IF19	IF18	IF17	IF16	IF15
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-13. Interrupt Status Register 3 (INT3)

IF15–IF22 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in [Table 13-3](#).

1 = Interrupt request present

0 = No interrupt request present

14.8.2 TIM Counter Registers

The two read-only TIM counter registers contain the high and low bytes of the value in the counter. Reading the high byte (TCNTH) latches the contents of the low byte (TCNTL) into a buffer. Subsequent reads of TCNTH do not affect the latched TCNTL value until TCNTL is read. Reset clears the TIM counter registers. Setting the TIM reset bit (TRST) also clears the TIM counter registers.

NOTE

If you read TCNTH during a break interrupt, be sure to unlatch TCNTL by reading TCNTL before exiting the break interrupt. Otherwise, TCNTL retains the value latched during the break.

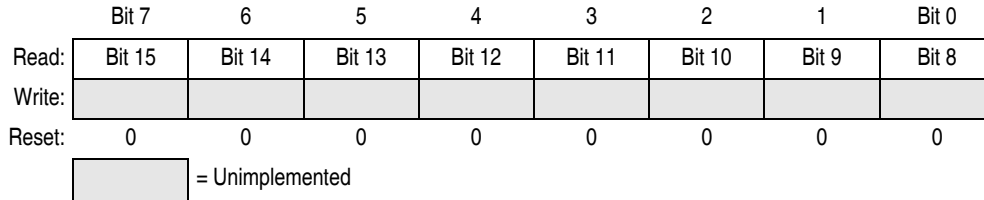


Figure 14-5. TIM Counter High Register (TCNTH)

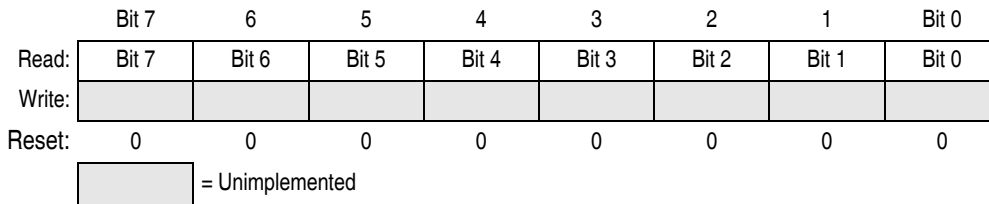


Figure 14-6. TIM Counter Low Register (TCNTL)

14.8.3 TIM Counter Modulo Registers

The read/write TIM modulo registers contain the modulo value for the counter. When the counter reaches the modulo value, the overflow flag (TOF) becomes set, and the counter resumes counting from \$0000 at the next timer clock. Writing to the high byte (TMODH) inhibits the TOF bit and overflow interrupts until the low byte (TMODL) is written. Reset sets the TIM counter modulo registers.

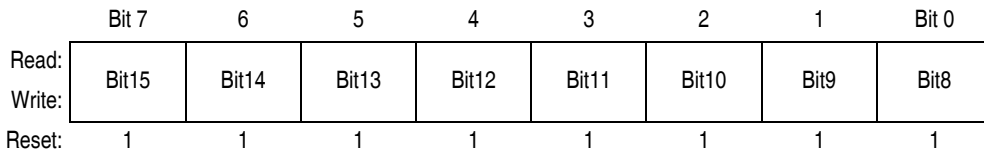


Figure 14-7. TIM Counter Modulo High Register (TMODH)

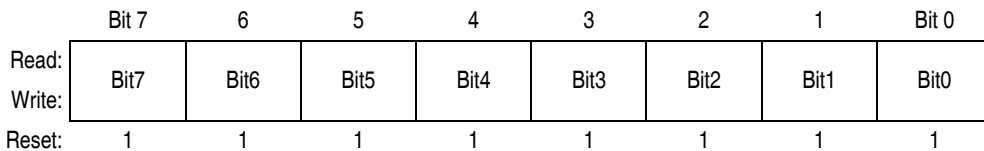


Figure 14-8. TIM Counter Modulo Low Register (TMODL)

NOTE

Reset the counter before writing to the TIM counter modulo registers.

TOVx — Toggle-On-Overflow Bit

When channel x is an output compare channel, this read/write bit controls the behavior of the channel x output when the counter overflows. When channel x is an input capture channel, TOVx has no effect.

1 = Channel x pin toggles on TIM counter overflow.

0 = Channel x pin does not toggle on TIM counter overflow.

NOTE

When TOVx is set, a counter overflow takes precedence over a channel x output compare if both occur at the same time.

CHxMAX — Channel x Maximum Duty Cycle Bit

When the TOVx bit is at 1, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100%. As [Figure 14-11](#) shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at the 100% duty cycle level until the cycle after CHxMAX is cleared.

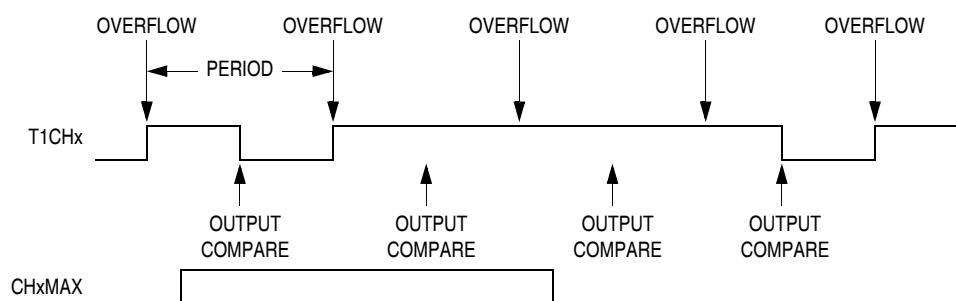


Figure 14-11. CHxMAX Latency

14.8.5 TIM Channel Registers

These read/write registers contain the captured counter value of the input capture function or the output compare value of the output compare function. The state of the TIM channel registers after reset is unknown.

In input capture mode ($MSxB:MSxA = 0:0$), reading the high byte of the TIM channel x registers (TCHxH) inhibits input captures until the low byte (TCHxL) is read.

In output compare mode ($MSxB:MSxA \neq 0:0$), writing to the high byte of the TIM channel x registers (TCHxH) inhibits output compares until the low byte (TCHxL) is written.

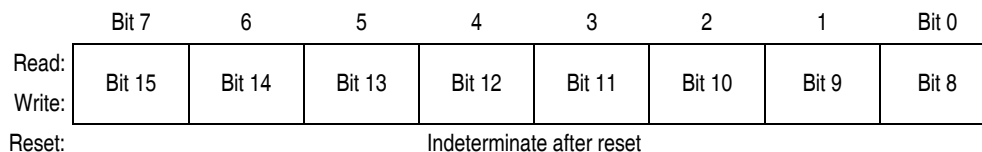


Figure 14-12. TIM Channel x Register High (TCHxH)

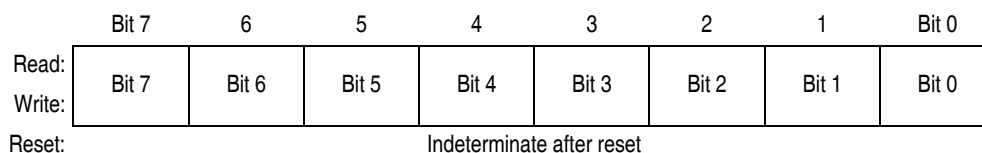


Figure 14-13. TIM Channel Register Low (TCHxL)

15.2.2.1 Break Status and Control Register

The break status and control register (BRKSCR) contains break module enable and status bits.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	BRKE	BRKA	0	0	0	0	0	0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 15-3. Break Status and Control Register (BRKSCR)

BRKE — Break Enable Bit

This read/write bit enables breaks on break address register matches. Clear BRKE by writing a 0 to bit 7. Reset clears the BRKE bit.

- 1 = Breaks enabled on 16-bit address match
- 0 = Breaks disabled

BRKA — Break Active Bit

This read/write status and control bit is set when a break address match occurs. Writing a 1 to BRKA generates a break interrupt. Clear BRKA by writing a 0 to it before exiting the break routine. Reset clears the BRKA bit.

- 1 = Break address match
- 0 = No break address match

15.2.2.2 Break Address Registers

The break address registers (BRKH and BRKL) contain the high and low bytes of the desired breakpoint address. Reset clears the break address registers.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
Write:								
Reset:	0	0	0	0	0	0	0	0

Figure 15-4. Break Address Register High (BRKH)

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Write:								
Reset:	0	0	0	0	0	0	0	0

Figure 15-5. Break Address Register Low (BRKL)

Table 15-4. WRITE (Write Memory) Command

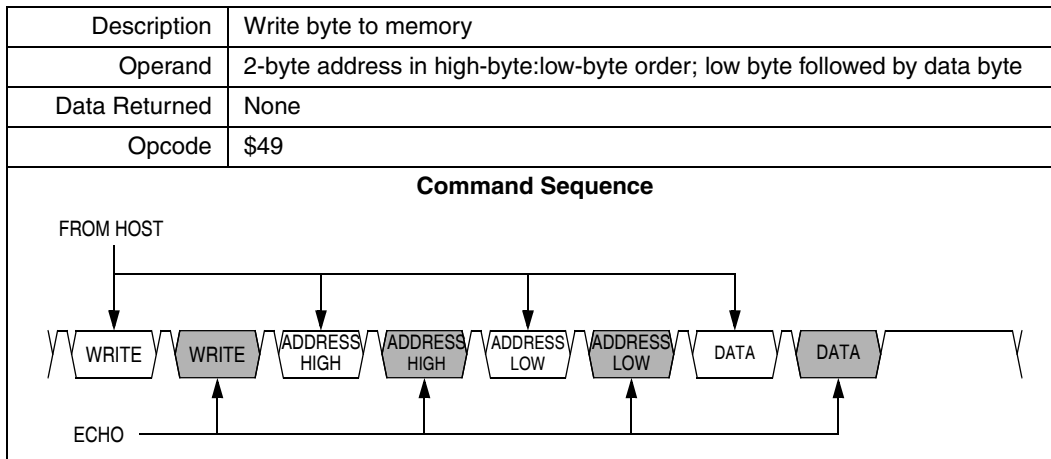


Table 15-5. IREAD (Indexed Read) Command

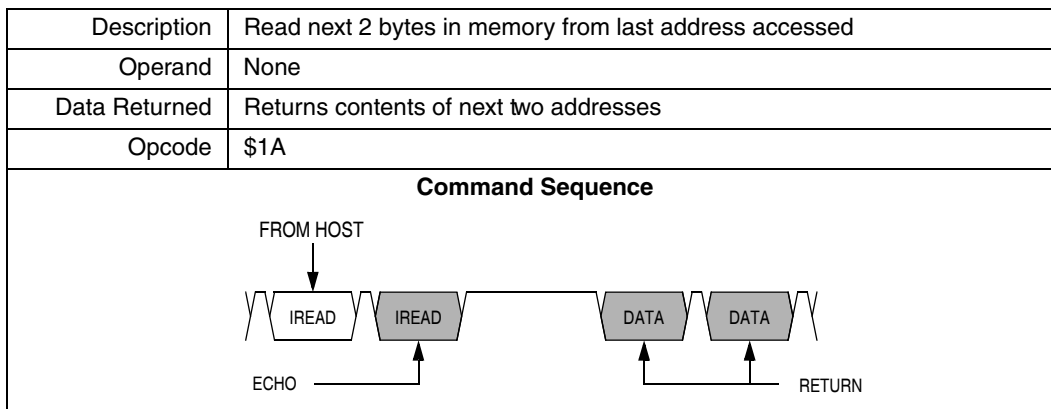
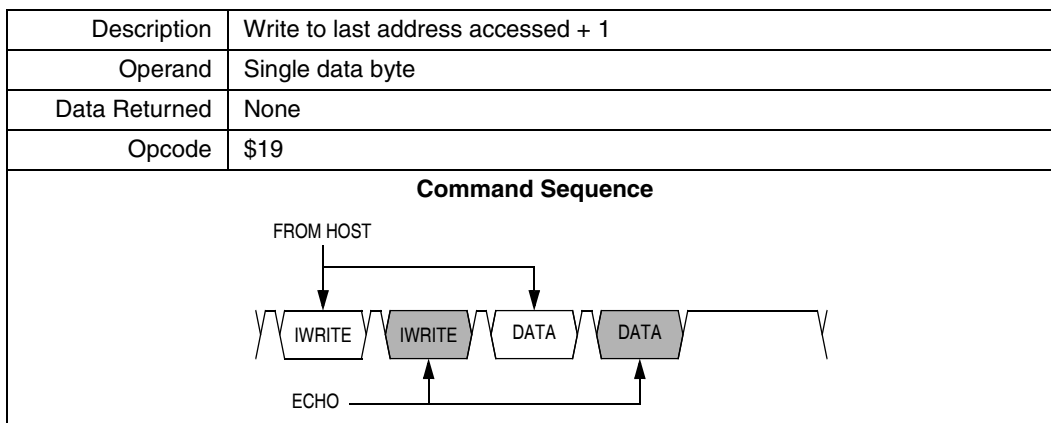


Table 15-6. IWRITE (Indexed Write) Command



A sequence of IREAD or IWRITE commands can access a block of memory sequentially over the full 64-Kbyte memory map.

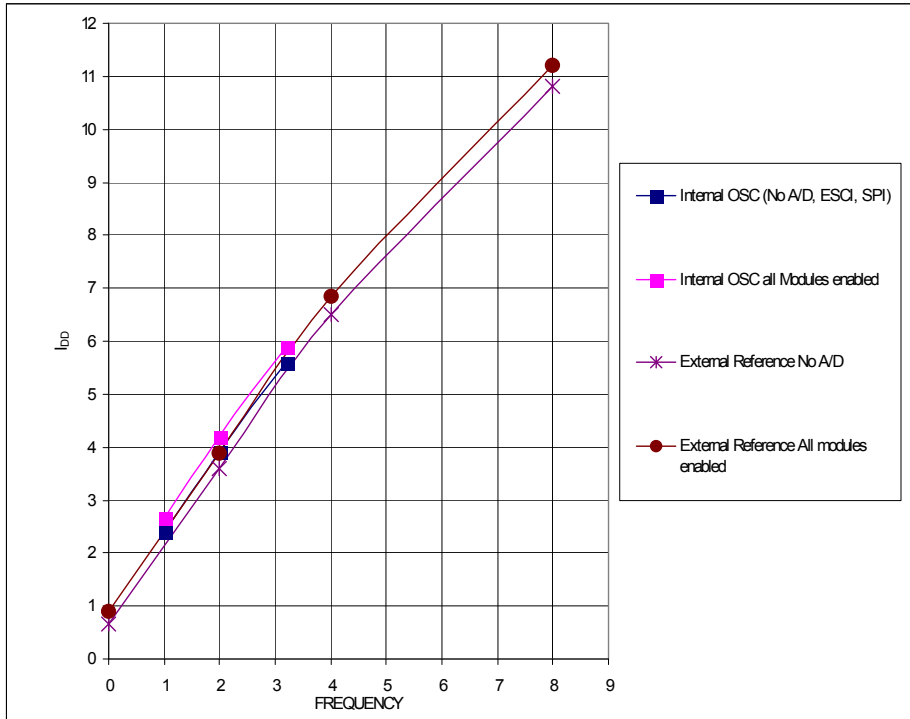


Figure 16-9. Typical 5-Volt Run Current versus Bus Frequency (25°C)

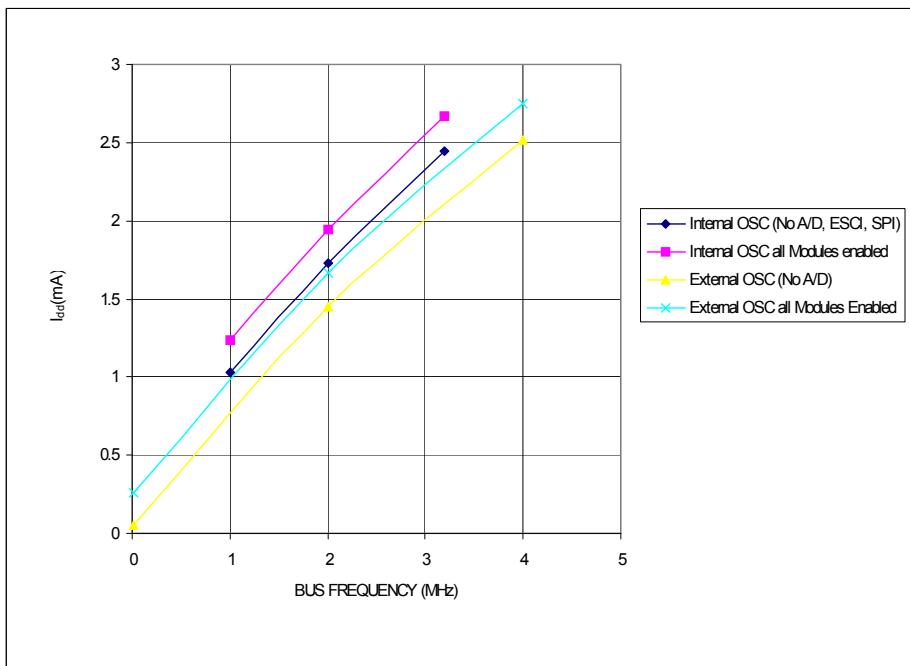


Figure 16-10. Typical 3-Volt Run Current versus Bus Frequency (25°C)

16.15 Memory Characteristics

Characteristic	Symbol	Min	Typ	Max	Unit
RAM data retention voltage ⁽¹⁾	V_{RDR}	1.3	—	—	V
FLASH program bus clock frequency	—	1	—	—	MHz
FLASH PGM/ERASE supply voltage (V_{DD})	$V_{PGM/ERASE}$	2.7	—	5.5	V
FLASH read bus clock frequency	$f_{Read}^{(2)}$	0	—	8 M	Hz
FLASH page erase time <1 K cycles >1 K cycles	t_{Erase}	0.9 3.6	1 4	1.1 5.5	ms
FLASH mass erase time	t_{MErase}	4	—	—	ms
FLASH PGM/ERASE to HVEN setup time	t_{NVS}	10	—	—	μ S
FLASH high-voltage hold time	t_{NVH}	5	—	—	μ S
FLASH high-voltage hold time (mass erase)	t_{NVHL}	100	—	—	μ S
FLASH program hold time	t_{PGS}	5	—	—	μ S
FLASH program time	t_{PROG}	30	—	40	μ S
FLASH return to read time	$t_{RCV}^{(3)}$	1	—	—	μ S
FLASH cumulative program hv period	$t_{HV}^{(4)}$	—	—	4	ms
FLASH endurance ⁽⁵⁾	—	10 k	100 k	—	Cycles
FLASH data retention time ⁽⁶⁾	—	15	100	—	Years

1. Values are based on characterization results, not tested in production.

2. f_{Read} is defined as the frequency range for which the FLASH memory can be read.

3. t_{RCV} is defined as the time it needs before the FLASH can be read after turning off the high voltage charge pump, by clearing HVEN to 0.

4. t_{HV} is defined as the cumulative high voltage programming time to the same row before next erase.

t_{HV} must satisfy this condition: $t_{NVS} + t_{NVH} + t_{PGS} + (t_{PROG} \times 32) \leq t_{HV}$ maximum.

5. Typical endurance was evaluated for this product family. For additional information on how Freescale Semiconductor defines *Typical Endurance*, please refer to Engineering Bulletin EB619.

6. Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how Freescale Semiconductor defines *Typical Data Retention*, please refer to Engineering Bulletin EB618.



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A.2.3 Improved Auto Wakeup Module (AWU)

The QYxA contains an AWU that has improved accuracy across voltage and temperature for typical testing.

- A new feature provides ability to run the AWU from an alternate source (internal oscillator or external crystal). This is an advantage for an application that needs more accurate AWU operation.
- On the QYxA AWU approximate time out will be 16 ms for short time out and 512 ms for long time out when running from the internal 32-kHz RC source.
- Finally, at lower voltages typical measurements have shown lower power consumption by the QYxA AWU.

A.2.3.1 Registers Affected

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IRQPUD	IRQEN	R	R	R	R	OSCENINSTOP	RSTEN
Write:								
Reset:	0	0	0	0	0	0	0	U
POR:	0	0	0	0	0	0	0	0

R = Reserved U = Unaffected

Figure A-5. Configuration Register 2 (CONFIG2)

Setting the OSCENINSTOP bit forces the AWU to use BUSCLKX2 as the source to this timeout.

A.2.4 New Power-on Reset Module (POR)

The QYxA POR re-arm voltage will have a minimum specification of 0.7 V while the QYx Classic POR re-arm was 0.1 V. The higher POR re-arm voltage provides added protection against brown out conditions.

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